

Technical Data Sheet

SYLGARDTM 164 Silicone Elastomer

FEATURES & BENEFITS

- Good flowability
- Low cost for silicone benefits
- Rapid room temp or heat accelerated cure
- Moderate thermal conductivity
- UL 94 V-0 flammability rating
- Rapid, versatile cure processing controlled by temperature
- Shorter room temp cure reduces cycle time
- Can be considered for uses requiring added flame resistance

COMPOSITION

• 1:1 mix ratio

Two-part, 1:1 mix, gray, general purpose encapsulant with good flowability and flame resistance and faster cure at room temperature

APPLICATIONS

• SYLGARDTM 164 Silicone Elastomer is suitable for general potting material for power supplies, connectors, sensors, industrial controls, transformers, amplifiers, high voltage resistor packs and relays.

TYPICAL PROPERTIES

Specification Writers: These values are not intended for use in preparing specifications.

Property	Unit	Result
Viscosity (Part A or Base)	cР	8925
	mPa-sec	8925
	Pa-sec	8.9
Viscosity (Part B or Catalyst)	cP	9175
	mPa-sec	9175
	Pa-sec	9.2
Specific Gravity (Uncured Part A or Base)		1.58
Specific Gravity (Uncured Part B or Catalyst)		1.57
Cure Time at 25°C	hours	0.6
Working Time at 25°C (Snap Time)	minutes	14
Durometer Shore A		61
Tear Strength (Die B)	ppi	0
	N/cm	2
Dielectric Strength	volts/mil	475
	kV/mm	19
Dielectric Constant at 100 Hz		3.33
Dielectric Constant at 100 kHz		3.28
Volume Resistivity	ohm*cm	1.1 E + 13
Dissipation Factor at 100 Hz		0.0078
Dissipation Factor at 100 kHz		0.0009
Thermal Conductivity	BTU/hr ft °F	0.37
	W/m $^{\circ}$ K	0.64
Linear CTE (by TMA)	ppm/°C	225
UL Flammability Classification	NA	94 V-0

TYPICAL PROPERTIES (Cont.)

Property	Unit	Result
Shelf Life at 25°C	months	15
UL RTI Rating	°C	150

DESCRIPTION

Dow silicone encapsulants are supplied as two-part liquid component kits. When liquid components are thoroughly mixed, the mixture cures to a flexible elastomer, which is well suited for the protection of electrical PCB system assembly applications. Dow silicone encapsulants cure without exotherm at a constant rate regardless of sectional thickness or degree of confinement. Dow silicone elastomers require no post cure and can be placed in service immediately following the completion of the cure schedule. Standard silicone encapsulants require a surface treatment with a primer in addition to good cleaning for adhesion while primerless silicone encapsulants require only good cleaning.

APPLICATION METHODS

Automated metered mixing and dispensing.

MIXING AND DE-AIRING

Dow silicone encapsulants are supplied as two-part liquid component kits. When liquid components are thoroughly mixed, the mixture cures to a flexible elastomer, which is well suited for the protection of electrical PCB system assembly applications. The 1:1 mix ratio is very robust in manufacturing environments and allows for some process and dispense equipment variation. Dow silicone encapsulants cure without exotherm at a constant rate regardless of sectional thickness or degree of confinement. Dow silicone elastomers require no post cure and can be placed in service immediately following the completion of the cure schedule.

Standard silicone encapsulants require a surface treatment with a primer in addition to good cleaning for adhesion while primerless silicone encapsulants require only good cleaning.

PREPARING SURFACES

In applications requiring adhesion, priming will be required for the silicone encapsulants. For best results, the primer should be applied in a very thin, uniform coating and then wiped off after application. After application, it should be thoroughly air dried prior to application of the silicone elastomer. Additional instructions for primer usage can be found in the information sheets specific to the individual primers.

PROCESSING/CURING

Thoroughly mixed Dow silicone encapsulants may be poured/dispensed directly into the container in which it is to be cured. Care should be taken to minimize air entrapment. When practical, pouring/dispensing should be done under vacuum, particularly if the component being potted or encapsulated has many small voids. If this technique cannot be used, the unit should be evacuated after the silicone encapsulant has been poured/ dispensed. Dow silicone encapsulants may be either room temperature (25°C/77°F) or heat cured. Room temperature cure encapsulants may also be heat accelerated for faster cure. Ideal cure conditions for each product are given in the product selection table.

POT LIFE AND CURE RATE

Cure reaction begins with the mixing process. Initially, cure is evidenced by a gradual increase in viscosity, followed by gelation and conversion to a solid elastomer. Pot life is defined as the time required for viscosity to double after Parts A and B (base and curing agent) are mixed and is highly temperature and application dependent. Please refer to the data table.

USEFUL TEMPERATURE RANGES

For most uses, silicone encapsulants should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low- and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations and should be adequately tested for the particular end-use environment. For lowtemperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

COMPATIBILITY

Certain materials, chemicals, curing agents and plasticizers can inhibit the cure of addition cure gels. Most notable of these include: organotin and other organometallic compounds, silicone rubber containing organotin catalyst, sulfur, polysulfides, polysulfones or other sulfur containing materials, unsaturated hydrocarbon plasticizers, and some solder flux residues. If a substrate or material is questionable with respect to potentially causing inhibition of cure, it is recommended that a small scale compatibility test be run to ascertain suitability in a given application. The presence of liquid or uncured product at the interface between the questionable substrate and the cured gel indicates incompatibility and inhibition of cure.

REPAIRABILITY

In the manufacture of electrical devices and PCB system assemblies it is often desirable to salvage or reclaim damaged or defective units. With most non-silicone rigid potting/encapsulating materials, removal or entry is difficult or impossible without causing excessive damage to internal circuitry. Dow silicone encapsulants can be selectively removed with relative ease, depending on the chosen remove method and technique and repairs or changes accomplished, and the repaired area repotted in place with additional product. To remove silicone elastomers, simply cut with a sharp blade or knife and tear and remove unwanted material from the area to be repaired. Sections of the adhered elastomer are best removed from substrates and circuitry by mechanical action such as scraping or rubbing and can be assisted by applying Dow OS fluids to swell the elastomer. Before applying additional encapsulant to a repaired device, roughen the exposed surfaces of the cured encapsulant with an abrasive paper and rinse with a suitable solvent and dry.

This will enhance adhesion and permit the repaired material to become an integral matrix with the existing encapsulant. Silicone prime coats are not recommended for adhering products to themselves.

PACKAGING INFORMATION

In general, Dow silicone 1:1 mix ratio encapsulants are supplied in nominal 0.45, 3.6, 18 and 200-kg (1, 8, 40 and 440-lb) containers, net weight. Dow silicone 10:1 mix ratio encapsulants are supplied in nominal 0.5, 5, 25 and 225-kg (1.1, 11, 55 and 495-lb) containers, net weight. Packaging options may vary by product

USABLE LIFE AND STORAGE

Shelf life is indicated by the "Use Before" date found on the product label. For best results, Dow silicone encapsulants should be stored at or below 25°C (77°F). Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen.

HANDLING PRECAUTIONS PRODUCT SAFETY INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND **HEALTH HAZARD** INFORMATION. THE SAFETY DATA SHEET IS AVAILABLE ON THE DOW WEBSITE AT WWW.CONSUMER.DOW.COM. OR FROM YOUR DOW SALES APPLICATION ENGINEER, OR DISTRIBUTOR, OR BY CALLING DOW CUSTOMER SERVICE.

LIMITATIONS

This product is neither tested nor represented as suitable for medical or pharmaceutical uses

HEALTH AND ENVIRONMENTAL INFORMATION

To support customers in their product safety needs, Dow has an extensive Product Stewardship organization and a team of Product Safety and Regulatory Compliance specialists available in each area.

For further information, please see our website, www.consumer.dow.com or consult your local Dow representative.

LIMITED WARRANTY INFORMATION – PLEASE READ CAREFULLY

The information contained herein is offered in good faith and is believed to be accurate. However, because conditions and methods of use of our products are beyond our control, this information should not be used in substitution for customer's tests to ensure that our products are safe, effective, and fully satisfactory for the intended end use. Suggestions of use shall not be taken as inducements to infringe any patent.

Dow's sole warranty is that our products will meet the sales specifications in effect at the time of shipment.

Your exclusive remedy for breach of such warranty is limited to refund of purchase price or replacement of any product shown to be other than as warranted.

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To discuss how we could work together to meet your specific needs, go to **www.consumer.dow.com** for a contact close to your location. Dow has customer service teams, science and technology centers, application support teams, sales offices, and manufacturing sites around the globe.

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